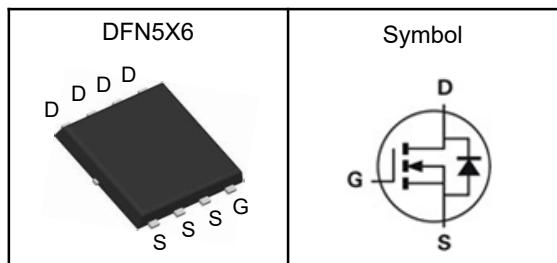


## N-Channel Enhancement Mode MOSFET

### Features

- High Speed Power Switching
- Reliable and Rugged
- ROHS Compliant
- 100% Avalanche Tested

### Pin Description



### Applications

- Power Management in Desktop Computer
- DC/DC Converters

$V_{DSS}$	60	V
$R_{DS(ON)-Typ}$	4.0	$m\Omega$
$I_D$	109	A

### Absolute Maximum Ratings ( $T_C=25^\circ C$ , Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
$V_{DSS}$	Drain-Source Voltage	60	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$T_J$	Maximum Junction Temperature	-55 to 150	$^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$I_{DM}^{①}$	Pulse Drain Current Tested	436	A
$I_D$	Continuous Drain Current	109	A
$P_D$	Maximum Power Dissipation	113	W
$E_{AS}$	Avalanche Energy, Single pulse	226	mJ

### Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JC}$	Thermal Resistance Junction-Case	1.1	$^\circ C/W$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature  $150^\circ C$ .

Note ③ : Surface Mounted on  $1in^2$  FR-4 board with 1oz.

**N-Channel Enhancement Mode MOSFET**
**Electrical Characteristics (T<sub>J</sub>=25°C, Unless Otherwise Noted)**

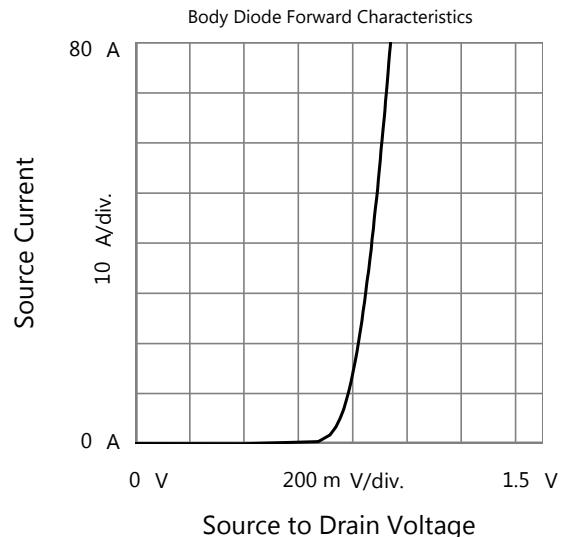
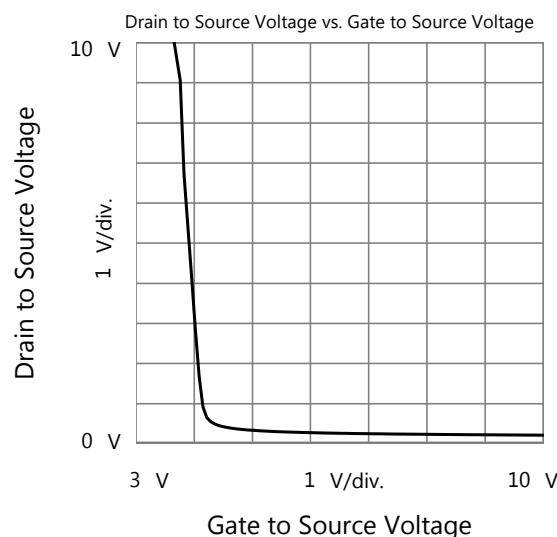
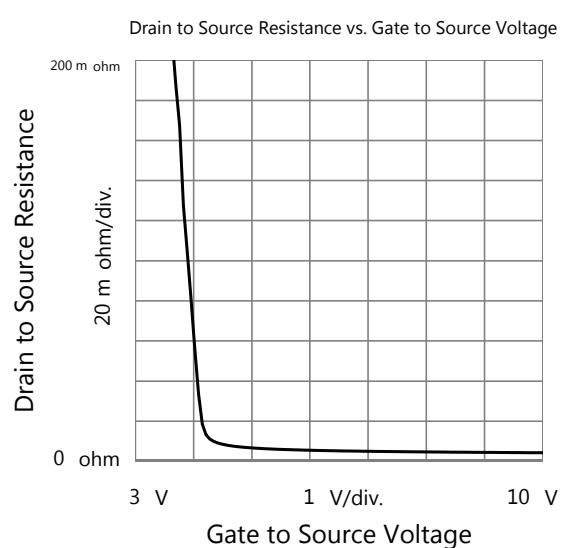
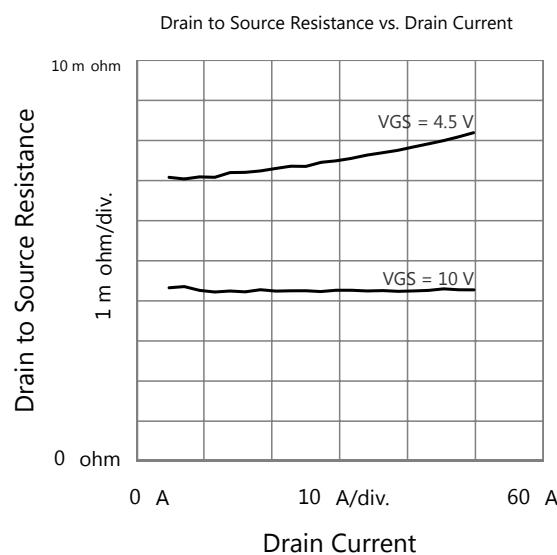
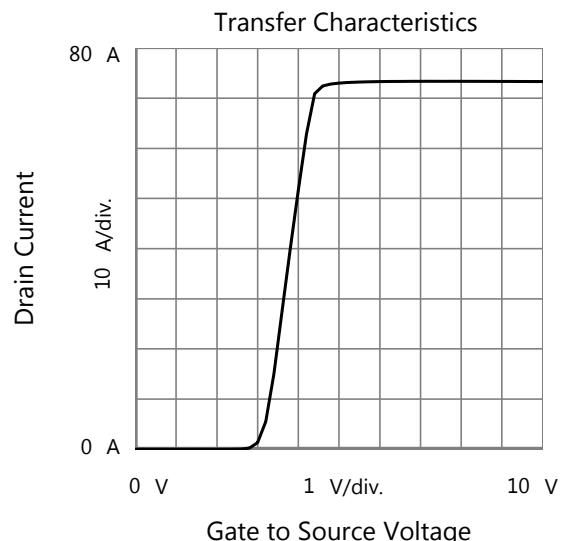
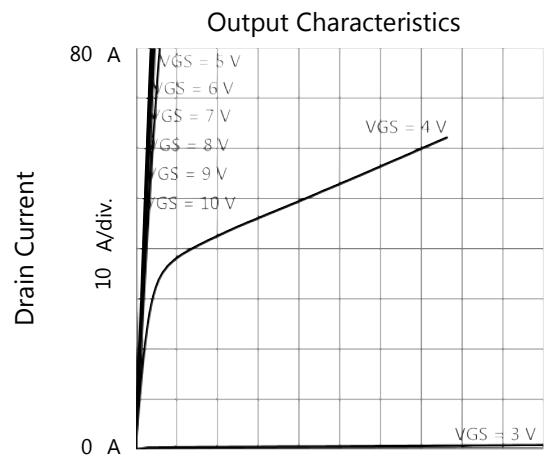
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Static Electrical Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	60	---	---	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	---	---	1	uA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1.0	---	2.5	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
R <sub>DS(ON)</sub>	Drain-Source On-state Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	4.0	5.3	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A	---	7.5	8.0	mΩ
<b>Dynamic Characteristics<sup>⑤</sup></b>						
R <sub>g</sub>	Gate Resistance	f = 1.0 MHz, V <sub>GS</sub> =0V	---	2.5	---	Ω
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, Freq.=1MHz	---	1920	---	pF
C <sub>oss</sub>	Output Capacitance		---	497	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	10	---	
T <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =48V, V <sub>GS</sub> =10V, I <sub>D</sub> =20A, R <sub>L</sub> =5Ω	---	16	---	nS
T <sub>r</sub>	Turn-on Rise Time		---	36	---	
T <sub>d(off)</sub>	Turn-off Delay Time		---	43	---	
T <sub>f</sub>	Turn-off Fall Time		---	14	---	
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =48V, V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	28	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	6.6	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	5.9	---	
<b>Source-Drain Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =15A, V <sub>GS</sub> =0V	---	---	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =40A, dI <sub>F</sub> / dt=100A/us	---	31	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	15	---	nC

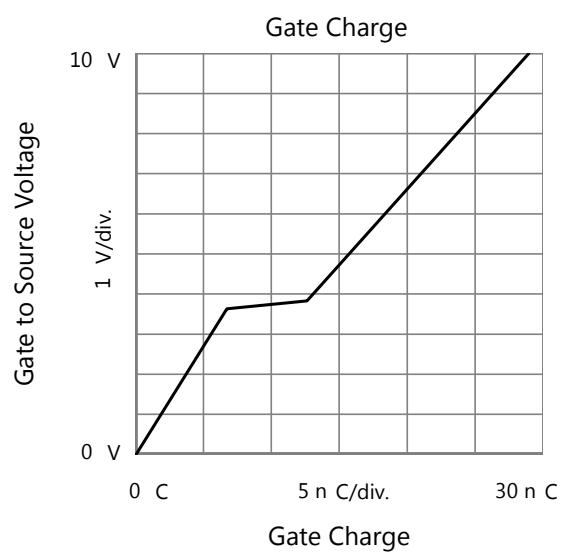
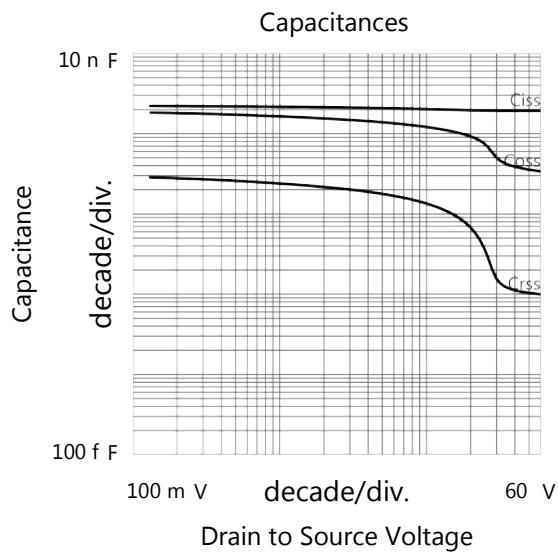
Note ④: Pulse test (pulse width≤300us, duty cycle≤2%).

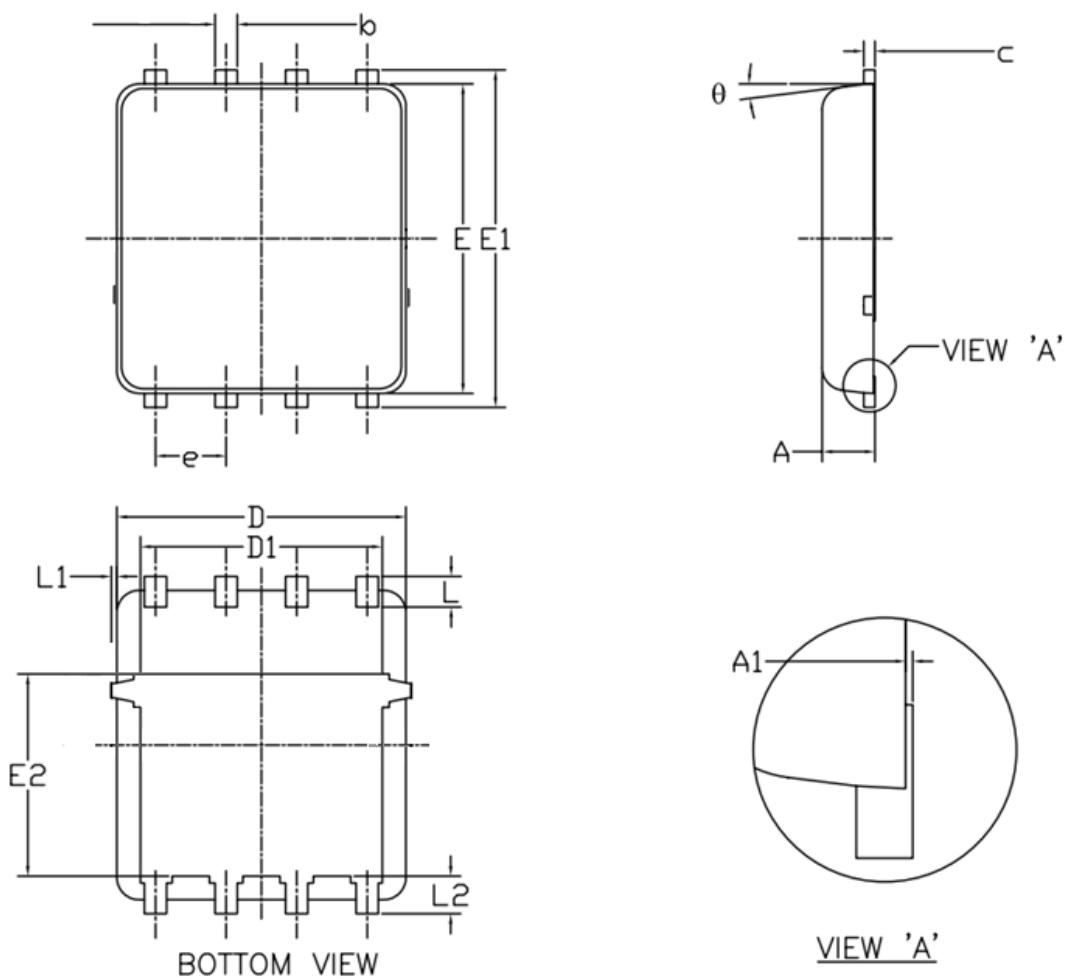
Note ⑤ : Guaranteed by design, not subject to production testing.

## N-Channel Enhancement Mode MOSFET

### Typical Characteristics



**N-Channel Enhancement Mode MOSFET**


**N-Channel Enhancement Mode MOSFET**
**DFN5X6-8L Package Outline Dimensions**


<b>Symbol</b>	<b>Dimensions (unit:mm)</b>			<b>Symbol</b>	<b>Dimensions (unit:mm)</b>		
	<b>Min</b>	<b>Typ</b>	<b>Max</b>		<b>Min</b>	<b>Typ</b>	<b>Max</b>
<b>A</b>	0.90	1.00	1.20	<b>E1</b>	5.90	6.10	6.35
<b>A1</b>	0.00	--	0.05	<b>E2</b>	3.38	3.58	3.92
<b>b</b>	0.30	0.40	0.51	<b>e</b>	1.27 BSC		
<b>c</b>	0.20	0.25	0.33	<b>L</b>	0.51	0.61	0.71
<b>D</b>	4.80	4.90	5.40	<b>L1</b>	--	--	0.15
<b>D1</b>	3.61	4.00	4.25	<b>L2</b>	0.41	0.51	0.61
<b>E</b>	5.65	5.80	6.06	<b>θ</b>	0°	--	12°